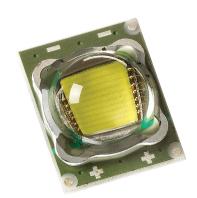


# SST-50 W LEDs



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#### **Features:**

- Extremely high optical output: Over 1,150 lumens from a single chip (white)
- Extremely high efficiency: Over 100 lumens per watt at 1.75A
- High thermal conductivity package junction to case thermal resistance of only 2.45  $^{\circ}\text{C/W}$
- Large, monolithic chip with uniform emitting area of 5 mm<sup>2</sup>
- Lumen maintenance of greater than 70% after 60,000 hours
- Environmentally friendly: RoHS compliant
- Variable drive currents: less than 1 A through 5 A
- High reliability
- · Electrically isolated thermal path

# **Applications**

- Replacement Lamps
- High Bay Lighting
- Street Lighting
- Consumer Portable

- Architectural Lighting
- · Retail Lighting
- Residential Lighting
- Spot Lighting





# **Technology Overview**

Luminus Big Chip LEDs<sup>™</sup> benefit from a suite of innovations in the fields of chip technology, packaging and thermal management. These breakthroughs allow illumination engineers and designers to achieve solutions that are high brightness and high efficiency.

#### **Luminus Technology**

Luminus' technology enables large area LED chips with uniform brightness over the entire LED chip surface. The optical power and brightness produced by these large monolithic chips enable solutions which replace arc and halogen lamps where arrays of traditional high power LEDs cannot.

#### **Packaging Technology**

Thermal management is critical in high power LED applications. With a thermal resistance from junction to case of 2.45° C/W. Luminus SST-50 LEDs have the lowest thermal resistance of any LED on the market. This allows the LED to be driven at higher current densities while maintaining a low junction temperature, thereby resulting in brighter solutions and longer lifetimes.

#### Reliability

Designed from the ground up, Luminus Big Chip LEDs are one of the most reliable light sources in the world today. Big Chip LEDs have passed a rigorous suite of environmental and mechanical stress tests, including mechanical shock, vibration, temperature cycling and humidity, and have been fully qualified for use in extreme high power and high current applications. With very low failure rates and median lifetimes that typically exceed 60,000 hours, Luminus Big Chip LEDs are ready for even the most demanding applications.

#### **Environmental Benefits**

Luminus LEDs help reduce power consumption and the amount of hazardous waste entering the environment. All Big Chip LED products manufactured by Luminus are RoHS compliant and free of hazardous materials, including lead and mercury.

# **Understanding Big Chip LED Test Specifications**

Every Luminus LED is fully tested to ensure that it meets the high quality standards expected from Luminus' products.

#### **Testing Temperature**

Luminus surface mount LEDs are typically tested with a 20 msec input pulse and a junction temperature of 25°C. Expected flux values in real world operation can be extrapolated based on the information contained within this product data sheet.

#### **Multiple Operating Points**

The tables on the following pages provide typical optical and electrical characteristics. Since the LEDs can be operated over a wide range of drive conditions (currents from less than 1.0 A to 5.0 A, and duty cycle from <1% to 100%), multiple drive conditions are possible.

SST-50 LEDs are production tested at 1.75 A.



# **SST-50 White Binning Structure**

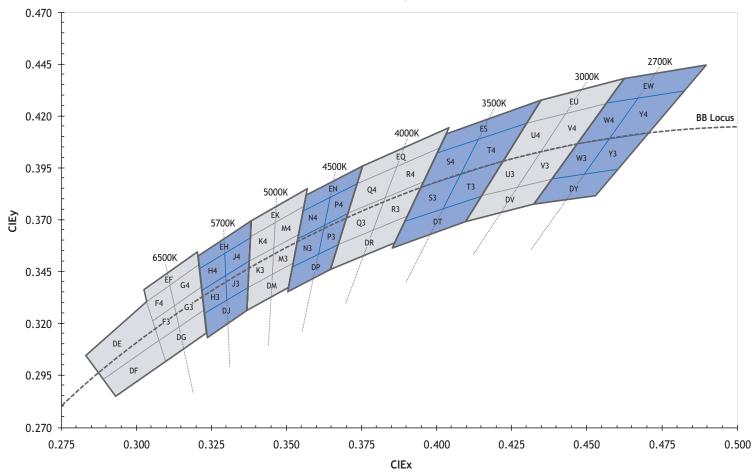
SST-50 LEDs are tested for luminous flux and chromaticity at a drive current of 1.75 A (350 mA/mm<sup>2</sup>) and placed into one of the following luminous flux (FF) and chromaticity (WW) bins:

Flux Bin (FF)	Minumum Flux (lm) @ 1.75A	Maximum Flux (lm) @ 1.75A
G2	300	325
G3	325	350
Н	350	375
H2	375	400
H3	400	425
J	425	450
J2	450	475
J3	475	500
K	500	530

<sup>\*</sup>Note: Luminus maintains a +/- 6% tolerance on flux measurements.

#### **Chromaticity Bins**

Luminus' Standard Chromaticity Bins: 1931 CIE Curve







The following tables describe the four chromaticity points that bound each chromaticity bin. Chromaticity bins are grouped together based on the color temperature.

6500K Chromaticity Bins			
Bin Code (WW)	CIEx	CIEy	
	0.307	0.311	
DG	0.322	0.326	
l bd	0.323	0.316	
	0.309	0.302	
	0.305	0.321	
F3*	0.313	0.329	
Lo	0.315	0.319	
	0.307	0.311	
	0.303	0.330	
F4*	0.312	0.339	
[ F4*	0.313	0.329	
	0.305	0.321	
	0.313	0.329	
C2*	0.321	0.337	
G3*	0.322	0.326	
	0.315	0.319	
	0.312	0.339	
CA¥	0.321	0.348	
G4*	0.321	0.337	
	0.313	0.329	
	0.302	0.335	
	0.320	0.354	
EF	0.321	0.348	
	0.303	0.330	
	0.283	0.304	
DE	0.303	0.330	
DE	0.307	0.311	
	0.289	0.293	
	0.289	0.293	
DE	0.307	0.311	
DF	0.309	0.302	
	0.293	0.285	

5700K Chromaticity Bins			
Bin Code (WW)	CIEx	CIEy	
	0.322	0.324	
LDJ	0.337	0.337	
	0.336	0.326	
	0.323	0.314	
	0.321	0.335	
H3*	0.329	0.342	
ПЭ	0.329	0.331	
	0.322	0.324	
	0.321	0.346	
H4*	0.329	0.354	
Π4	0.329	0.342	
	0.321	0.335	
	0.329	0.342	
J3*	0.337	0.349	
] ,3	0.337	0.337	
	0.330	0.331	
	0.329	0.354	
J4*	0.338	0.362	
J- <del>1</del>	0.337	0.349	
	0.329	0.342	
	0.320	0.352	
EH	0.338	0.368	
ЕП	0.338	0.362	
	0.321	0.346	

<sup>\*</sup>Sub-bins within ANSI defined quadrangles per ANSI C78.377-2008





500	5000K Chromaticity Bins			
Bin Code (WW)	CIEx	CIEy		
	0.338	0.368		
EK	0.356	0.384		
EN	0.355	0.376		
	0.338	0.362		
	0.337	0.349		
K3*	0.345	0.355		
N3"	0.345	0.343		
	0.337	0.337		
	0.338	0.362		
I/ 4 *	0.347	0.369		
K4*	0.345	0.355		
	0.337	0.349		
	0.345	0.355		
142×	0.353	0.349		
M3*	0.352	0.372		
	0.344	0.343		
	0.346	0.369		
M4*	0.355	0.376		
IVI <del>4</del> "	0.353	0.362		
	0.345	0.355		
	0.337	0.337		
DM	0.352	0.349		
DM	0.350	0.337		
	0.336	0.326		

4500K Chromaticity Bins			
Bin Code (WW)	CIEx	CIEy	
	0.356	0.384	
EN	0.376	0.396	
EIN EIN	0.374	0.387	
	0.355	0.374	
	0.353	0.360	
N3*	0.361	0.366	
IN5"	0.359	0.352	
	0.351	0.347	
	0.355	0.374	
N4*	0.364	0.381	
IN4"	0.361	0.366	
	0.353	0.360	
	0.361	0.366	
P3*	0.370	0.373	
P3"	0.367	0.358	
	0.359	0.352	
	0.364	0.381	
D4*	0.374	0.387	
P4*	0.370	0.373	
	0.361	0.366	
	0.351	0.347	
DD	0.367	0.358	
DP	0.364	0.346	
	0.350	0.335	

\*Sub-bins within ANSI defined quadrangles per ANSI C78.377-2008



4000K Chromaticity Bins			
Bin Code (WW)	CIEx	CIEy	
	0.376	0.396	
EQ	0.404	0.414	
	0.401	0.404	
	0.374	0.387	
	0.370	0.373	
02*	0.382	0.380	
Q3*	0.378	0.365	
	0.367	0.358	
	0.374	0.387	
0.4*	0.387	0.396	
Q4*	0.382	0.380	
	0.370	0.373	
	0.382	0.380	
D2*	0.395	0.388	
R3*	0.390	0.372	
	0.378	0.365	
	0.387	0.396	
D4*	0.401	0.404	
R4*	0.395	0.388	
	0.382	0.380	
	0.367	0.358	
DD	0.390	0.372	
DR	0.386	0.359	
	0.364	0.346	

<sup>\*</sup>Sub-bins within ANSI defined quadrangles per ANSI C78.377-2008



WW

FF



# **Product Shipping & Labeling Information**

All SST-50 products are packaged and labeled with their respective bin as outlined in the tables from pages 3 to 7. When shipped, each package will only contain one bin. The part number designation is as follows:

WNNX

Product Family	Chip Area	Color	Package Configuration	Flux Bin	Chromaticity Bin
Surface Mount (Lens)	5.0 mm <sup>2</sup>	CCT & CRI See Note 1 below	Internal Code	See page 3 for bins	See page 4-7 for bins

F21

Note 1: WNNX nomenclature corresponds to the following:

50

W = White

SST

NN = color temperature, where:

65 corresponds to 6500K

X = color rendering index, where:

S (standard) corresponds to a typical CRI of 70

Note 2: Some flux and chromaticity bins may have limited availability. Application specific bin kits, consisting of multiple bins, may be available. For ordering information, please refer to page 15 and reference PDS-001848: SST-50 Binning & Labeling document.

#### Example:

The part number SST-50-W65S-F21-J3-G4 refers to a 6500K standard CRI white, SST-50 emitter, with a flux range from 475 to 500 lumens and a chromaticity value within the box defined by the four points (0.313, 0.338), (0.321, 0.348), (0.322, 0.336), (0.312, 0.328).



#### Electrical Characteristics<sup>1</sup>

#### Optical and Electrical Characteristics (T<sub>1</sub> = 25 °C)

Drive Condition <sup>2</sup>		1.75 A	
Parameter	Symbol	Test Current	Unit
Current Density	j	0.35	A/mm <sup>2</sup>
	$V_{F,min}$	2.5	V
Forward Voltage	$V_{F,\mathrm{typ}}$	3.2	V
	V <sub>F, max</sub>	3.9	V

#### **Common Characteristics**

Parameter	Symbol	Values	Unit
Viewing Angle	2 θ <sub>1/2</sub>	100	
Emitting Area	А	5.0	mm²
Emitting Area Dimensions		2.25 x 2.25	mm×mm
Forward Voltage Temperature Coefficient⁴		-4.4	mV/ºC

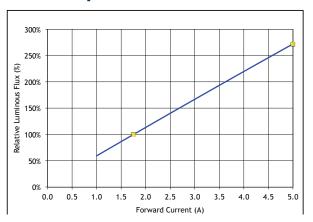
#### **Absolute Maximum Ratings**

Parameter	Symbol	Values	Unit
Maximum Current <sup>5</sup>		5.0	А
Maximum Reverse Current		N/A	
Maximum Junction Temperature <sup>6</sup>	T <sub>j-max</sub>	150	°C
Storage Temperature Range		-40/+100	°C

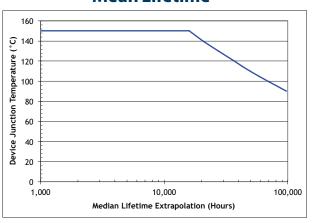
- Note 1: Listed drive conditions are typical for common applications. SST-50 White devices can be driven at currents ranging from <1A to 5A and at duty cycles ranging from <1% to 100%. Drive current and duty cycle should be adjusted as necessary to maintain the junction temperature desired to meet application lifetime requirements.
- Note 2: Unless otherwise noted, values listed are typical.
- Note 3: Forward voltage temperature coefficient at 1.75A. Contact Luminus for value at other drive conditions.
- Note 4: SST-50 devices are designed for operation to an absolute maximum forward drive current 5A. Product lifetime data is specified at recommended forward drive currents. Sustained operation at absolute maximum currents will result in a reduction of device lifetime compared to recommended forward drive currents. Actual device lifetimes will also depend on junction temperature. Refer to APN-001521: Reliability Application Note for SST-50-W for further information. In pulsed operation, rise time from 10-90% of forward current should be larger than 0.5 microseconds.
- Note 5: Lifetime dependent on LED junction temperature. Thermal calculations based on input power and thermal management system should be performed to ensure T<sub>J</sub> is maintained below T<sub>imax</sub> rating or life will be reduced. Refer to APN-001521 for further information.
- Note 6: CIE measurement uncertainty for white devices is estimated to be +/- 0.01.
- Note 7: Special design considerations must be observed for operation under 1A. Please contact Luminus for further information.
- Note 8: Caution must be taken not to stare at the light emitted from these LEDs. Under special circumstances, the high intensity could damage the eye.



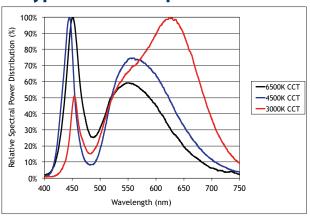
# Relative Output Flux vs. Forward Current<sup>1</sup>



## Mean Lifetime<sup>2</sup>



# **Typical Relative Spectral Power<sup>4</sup>**



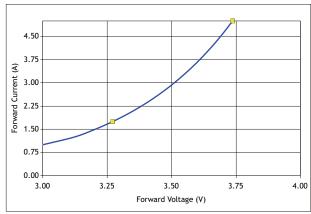
#### Note 1: Yellow squares indicate typical operating conditions.

# Note 2: Mean expected lifetime in dependence of junction temperature at 0.35 A/mm² in continuous operation. Lifetime defined as time to 70% of initial intensity. Based on lifetime test data of uncoated GaN devices at this time. Data can be used to model failure rate over typical product lifetime (contact Luminus for lifetime reliability test data for 1A/mm² condition).

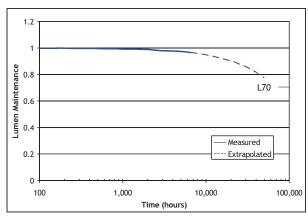
Note 3: Lumen maintenance in dependence of time at 0.35 A/mm<sup>2</sup> in continuous operation with junction temperatures of 100 °C.

Note 4: Typical spectrum at current density of 0.35 A/mm<sup>2</sup> in continuous operation.

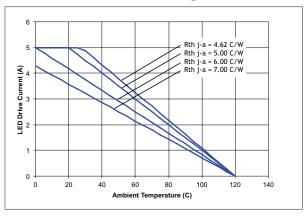
# Forward Current vs. Forward Voltage



#### Lumen Maintenance vs. Time<sup>3</sup>

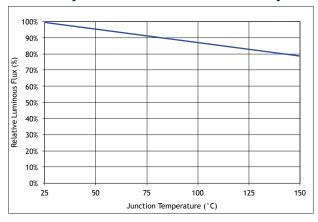


# **Current Derating Curve**



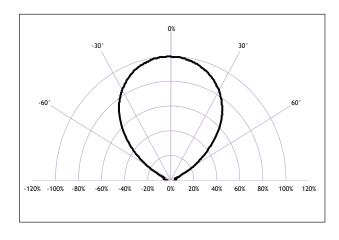


# **Relative Output Flux vs. Junction Temperature**

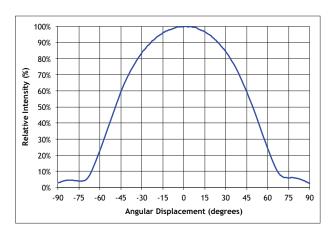


# **Typical Radiation Pattern**

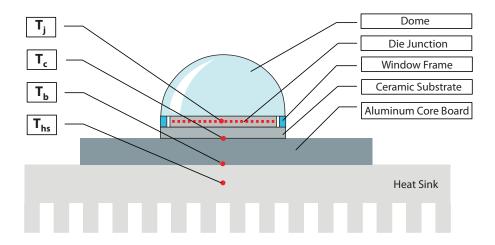
#### **Typical Polar Radiation Pattern for White**



#### **Typical Angular Radiation Pattern for White**



#### **Thermal Resistance**



# Typical Thermal Resistance, junction to case

R <sub>j-c</sub> 1	2.45 °C/W
R <sub>j-b</sub> <sup>1</sup>	4.28 °C/W
R <sub>j-hs</sub> <sup>2</sup>	4.39 °C/W

Note 1: Thermal resistance values are based on FEA model results correlated to measured  $R_{\theta i ext{-}hs}$  data.

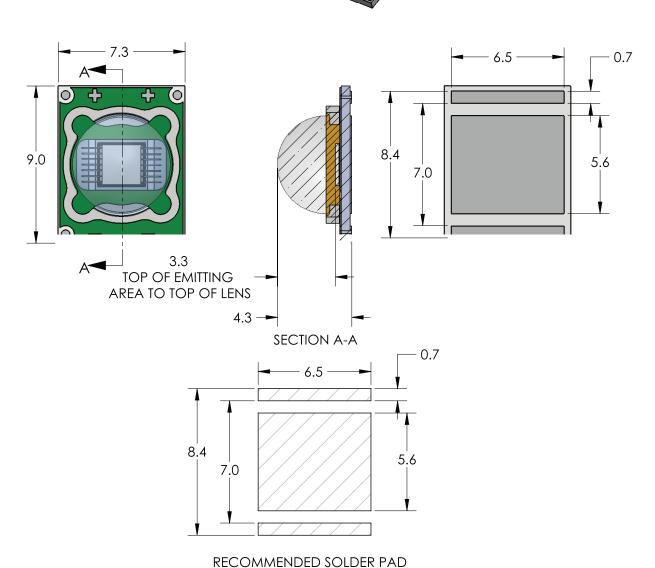
Note 2: Thermal resistance is measured using a SAC305 solder, a Bergquist Al-clad MCPCB, and eGraf 1205 thermal interface material.



## **Mechanical Dimensions – SST-50 Emitter**

LENS——FRAME
SUBSTRATE

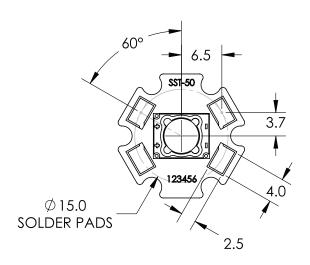
#### **DIMENSIONS IN MILLIMETERS**

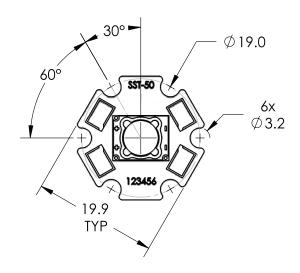


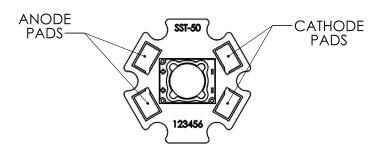
For detailed drawing please refer to DWG-001358 document

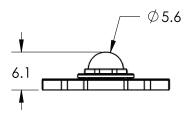


## **Mechanical Dimensions - SST-50 Star Board**











Note 1: Recommended mounting screw: M3 or #4

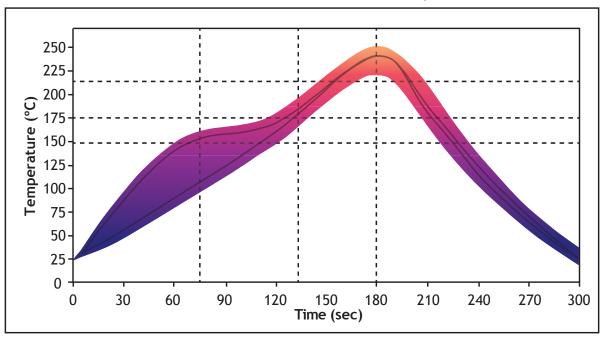
Note 2: All dimensions in millimeters

Note 3: anode pads on board are interconnected. All cathode pads on board are interconnected



#### **Solder Profile**

#### **SAC 305 Reflow Profile Window For Low Density Boards**



#### Lead free solder guideline for low density boards

Solder Profile Stage	Lead-Free Solder	Lead-based Solder
Profile length, Ambient to Peak	2.75 - 3.5 minutes	2.75 - 3.5 minutes
Time Maintained Above: Temperature	217 ℃	217 ℃
Time Maintained Above: Time	30 - 60 seconds	30 - 60 seconds
Cooldown Rate	≤4º C/sec	≤4º C/sec
Cooldown Duration	45 ± 15 sec	45 ± 15 sec

Note 1: Temperatures are taken and monitored at the component copper layer.

Note 2: Optimum profile may differ due to oven type, circuit board or assembly layout.

Note 3: Recommended lead free, no-clean solder: AIM NC254-SAC305.

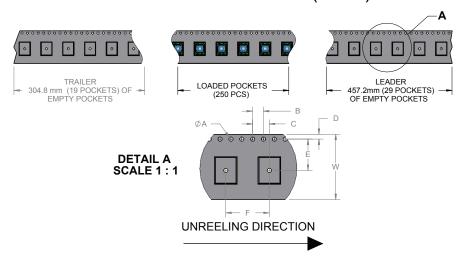
Note 4: Refer to APN-001473 soldering and handling application note for additional solder profiles and details.

Note 5: MSL-2A for SST parts only. The SSR product has no moisture sensitivity rating.

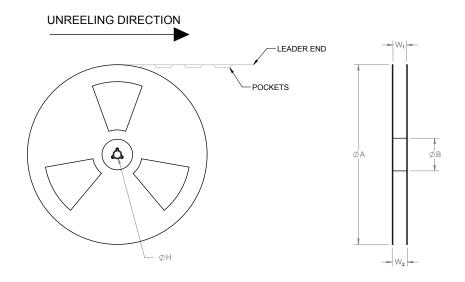


# **Tape and Reel Drawing of SST-50**

# DIMENSIONS ARE IN mm. (INCH)



TAPE DIMENSIONS							
W	ØΑ	В	C D		E	F	
24.0 (.945)	1.5 (.059)	3.9 (.157)	6.1 (.241)	1.7 (.069)	11.5 (.453)	16.0 (.630)	



REEL DIMENSIONS									
Ø۵	١	<b>W</b> 1		W <sub>2</sub>		ØΒ		ØΗ	
Ø330.2	(13.0)	25	(.984)	27.8	(1.094)	60.0	(2.362)	Ø 13.0	(.512)





# **Ordering Information**

Ordering Part Number 1,2	Color	Description
SST-50-WDLS-F21/T21-GG150	6500K White 5700K White	White Big Chip LED™ SST-50 surface mount device consisting of a 5mm² LED on a ceramic substrate,
SST-50-WCLS-F21/T21-GG450	4500K White 4000K White	F21- tray pack, T21- tape & reel pack
SSR-50-WDLS-R21-GG150	6500K White 5700K White	SSR-50 evaluation module consisting of a SST-50 surface mount device mounted on
SSR-50-WCLS-R21-GG450	4500K White 4000K White	an aluminum star board

Note 1: GG150 - denotes a bin kit comprising of all flux and chromaticity bins at the 6500K and 5700K color points

 $\mathsf{GG450}\text{-} denotes\ a\ bin\ kit\ comprising\ of\ all\ flux\ and\ chromaticity\ bins\ at\ the\ 4500K\ and\ 4000K\ color\ points$ 

Note 2: For ordering information on all available bin kits, please see PDS-001848: SST-50 Binning & Labeling document

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